



Attorney Docket No.: PATENT
SSI-04001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

William Dale Jones

Serial No.: 10/680,783

Filed: October 6, 2003

For: **HIGH-PRESSURE CHAMBER FOR
A SEMICONDUCTOR WAFER**

) Group Art Unit: 1765

) Examiner:

) **INFORMATION DISCLOSURE**
) **STATEMENT**

) 162 N. Wolfe Road
) Sunnyvale, CA 94086
) (408) 530-9700

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #53495); (EFS ID #53497); (EFS ID #53498); and (EFS ID #53499). Applicants have become aware of the following printed publication which may be material to the examination of this application:

- Chinese Publication No. CN 1399790 A;
- German Publication No. DE 36 08 783 A1;
- German Publication No. DE 198 60 084 A1;
- European Publication No. EP 0 244 951 A2;
- European Publication No. EP 0 272 141 A2;
- European Publication No. EP 0 453 867 A1;
- European Publication No. EP 0 572 913 A1;
- European Publication No. EP 0 587 168 A1;
- European Publication No. EP 0 679 753 B1;
- European Publication No. EP 0 903 775 A2;
- French Publication No. FR 1 499 491;

- Great Britain Publication No. GB 2 003 975;
- Great Britain Publication No. GB 2 193 482;
- Japanese Patent Abstract JP 2-148841;
- Japanese Patent Abstract JP 2-209729;
- Japanese Patent Abstract JP 8-186140;
- Japanese Patent Abstract JP 10-144757;
- Japanese Patent Abstract JP 10-335408;
- Japanese Patent Abstract JP 11-200035;
- Japanese Patent Abstract JP 56-142629;
- Japanese Patent Abstract JP 60-238479;
- Japanese Patent Abstract JP 60-246635;
- Japanese Patent Abstract JP 61-231166;
- Japanese Patent Abstract JP 62-125619;
- Japanese Patent Abstract JP 63-303059;
- Japanese Patent Abstract JP 2000/106358;
- Swiss Publication No. SE 251213;
- PCT Publication No. WO 87/07309;
- PCT Publication No. WO 91/12629;
- PCT Publication No. WO 99/18603;
- PCT Publication No. WO 00/36635;
- PCT Publication No. WO 01/10733 A1;
- PCT Publication No. WO 01/33615 A3;
- PCT Publication No. WO 01/55628 A1;
- PCT Publication No. WO 01/68279 A2;
- PCT Publication No. WO 01/74538 A1;
- PCT Publication No. WO 01/78911 A1;
- PCT Publication No. WO 01/85391 A2;
- PCT Publication No. WO 01/94782 A3;
- PCT Publication No. WO 02/16051 A2;
- PCT Publication No. WO 03/030219 A2;
- Hideaki Itakura et al., "Multi-Chamber Dry Etching System", Solid State Technology, April 1982, pp. 209-214;


- Sun, Y.P. et al., "Preparation of Polymer-Protected Semiconductor Nanoparticles Through the Rapid Expansion of Supercritical Fluid Solution," Chemical Physics Letters, pp. 585-588, May 22, 1998;
- Dahmen, N. et al., "Supercritical Fluid Extraction of Grinding and Metal Cutting Waste Contaminated with Oils," Supercritical Fluids - Extraction and Pollution Prevention, ACS Symposium Series, Vol. 670, pp. 270-279, 21 Oct 1997;
 - Xu, C. et al., "Submicron-Sized Spherical Yttrium Oxide Based Phosphors Prepared by Supercritical CO₂-Assisted aerosolization and pyrolysis," Appl. Phys. Lett., Vol. 71, No.12, September 22, 1997, pp. 1643-1645;
 - Courtecuisse, V.G. et al., "Kinetics of the Titanium Isopropoxide Decomposition in Supercritical Isopropyl Alcohol," Ind. Eng. Chem. Res., Vol. 35, No. 8, pp. 2539-2545, Aug 1996;
 - Gallagher-Wetmore, P. et al., "Supercritical Fluid Processing: A New Dry Technique for Photoresist Developing," SPIE Vol. 2438, pp.694-708, Jun. 1995.
 - McHardy, J. et al., "Progress in Supercritical CO₂ Cleaning," SAMPE Jour., Vol. 29, No. 5, pp. 20-27, September 1993;
 - Purtell, R, et al., "Precision Parts Cleaning using Supercritical Fluids," J. Vac, Sci, Technol. A. Vol. 11, No. 4, July 1993, pp. 1696-1701;
 - Hansen, B.N. et al., "Supercritical Fluid Transport - Chemical Deposition of Films," Chem. Mater., Vol. 4, No. 4, pp, 749-752, 1992;
 - Hybertson, B.M. et al., "Deposition of Palladium Films by a Novel Supercritical Fluid Transport Chemical Deposition Process," Mat. Res. Bull., Vol. 26, pp. 1127-1133, 1991;
 - Ziger, D. H. et al., "Compressed Fluid Technology: Application to RIE-Developed Resists," AiChE Jour., Vol. 33, No. 10, pp. 1585- 1591, October 1987;
 - Matson, D.W. et al., "Rapid Expansion of Supercritical Fluid Solutions: Solute Formation of Powders, Thin Films, and Fibers," Ind. Eng. Chem. Res., Vol. 26, No. 11, pp. 2298-2306, 1987;
 - Tolley, W.K. et al., "Stripping Organics from Metal and Mineral Surfaces using Supercritical Fluids," Separation Science and Technology, Vol. 22, pp. 1087-1101, 1987;
 - Joseph L. Foszcz, "Diaphragm Pumps Eliminate Seal Problems", Plant Engineering , pp. 1-5, February 1, 1996; and

- Bob Agnew, "WILDEN Air-Operated Diaphragm Pumps", Process & Industrial Training Technologies, Inc., 1996.

This Information Disclosure Statement under 37 C.F.R. §§ 1.56 and 1.97 is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that anyone or more of these citations constitutes prior art.

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 1-12-04

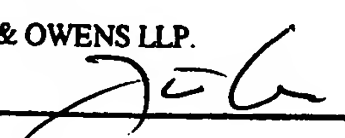
By: 
Thomas B. Haverstock
Reg. No.: 32,571

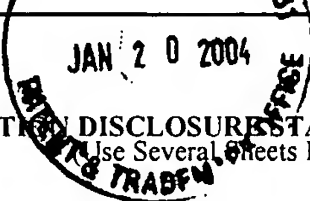
Attorneys for Applicant

CERTIFICATE OF MAILING (37 CFR § 1.8(a))

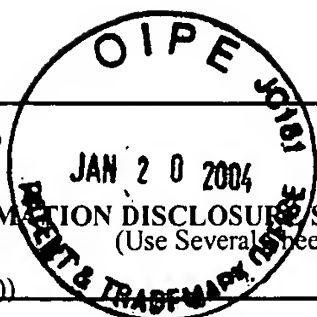
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- 4 -

HAVERSTOCK & OWENS LLP.
Date: 1-12-04 By: 

FORM PTO-1449 (Modified)				U.S. Department of Commerce Patent and Trademark Office		Attorney Docket No.: SSI-04001		Serial No.: 10/680,783	
INFORMATIONAL DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary)						Applicant: William Dale Jones			
(37 CFR § 1.98(b))						Filing Date: October 6, 2003		Group Art Unit: 1765	
FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS									
		Document Number	Publication Date	Country / Patent Office	Class	Subclass	Translation		
							Yes	No	
	AA	CN 1399790 A	02/26/03	China	H01L	21/00		X	
	AB	DE 36 08 783 A1	09/17/87	Germany	C30B	25/12		X	
	AC	DE 198 60 084 A1	07/06/00	Germany	H01L	21/3213		X	
	AD	EP 0 244 951 A2	11/11/87	EPO	H01L	21/00		X	
	AE	EP 0 272 141 A2	06/22/88	EPO	H01L	21/00		X	
	AF	EP 0 453 867 A1	10/30/91	EPO	F16K	51/02		X	
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EXAMINER:					Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.				

FORM PTO-1449 (Modified) INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary) (37 CFR § 1.98(b))	U.S. Department of Commerce Patent and Trademark Office	Attorney Docket No.: SSI-04001 Applicant: William Dale Jones Filing Date: October 6, 2003	Serial No.: 10/680,783 Group Art Unit: 1765
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FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS

		Document Number	Publication Date	Country / Patent Office	Class	Subclass	Translation	
							Yes	No
	BJ	WO 01/74538 A1	10/11/01	PCT	B24C	1/00		X
	BK	WO 01/78911 A1	10/25/01	PCT	B08B	3/00		X
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	BM	WO 01/94782 A3	12/13/01	PCT	F04B	43/02		X
	BN	WO 02/16051 A2	02/28/02	PCT	B05D			X
	BO	WO 03/030219 A2	10/04/03	PCT	H01L			X

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

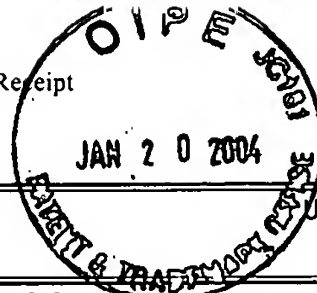
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	BQ	Sun, Y.P. et al., "Preparation of Polymer-Protected Semiconductor Nanoparticles Through the Rapid Expansion of Supercritical Fluid Solution," Chemical Physics Letters, pp. 585-588, May 22, 1998.
	BR	Dahmen, N. et al., "Supercritical Fluid Extraction of Grinding and Metal Cutting Waste Contaminated with Oils," Supercritical Fluids - Extraction and Pollution Prevention, ACS Symposium Series, Vol. 670, pp. 270-279, 21 Oct 1997.
	BS	Xu, C. et al., "Submicron-Sized Spherical Yttrium Oxide Based Phosphors Prepared by Supercritical CO ₂ -Assisted aerosolization and pyrolysis," Appl. Phys. Lett., Vol. 71, No. 12, September 22, 1997, pp. 1643-1645.
	BT	Courtecuisse, V.G. et al., "Kinetics of the Titanium Isopropoxide Decomposition in Supercritical Isopropyl Alcohol," Ind. Eng. Chem. Res., Vol. 35, No. 8, pp. 2539-2545, Aug 1996.
	BU	Gallagher-Wetmore, P. et al., "Supercritical Fluid Processing: A New Dry Technique for Photoresist Developing," SPIE Vol. 2438, pp. 694-708, Jun. 1995.
	BV	McHardy, J. et al., "Progress in Supercritical CO ₂ Cleaning," SAMPE Jour., Vol. 29, No. 5, pp. 20-27, September 1993.
	BW	Purtell, R. et al., "Precision Parts Cleaning using Supercritical Fluids," J. Vac. Sci. Technol. A. Vol. 11, No. 4, July 1993, pp. 1696-1701.
	BX	Hansen, B.N. et al., "Supercritical Fluid Transport - Chemical Deposition of Films," Chem. Mater., Vol. 4, No. 4, pp. 749-752, 1992.
	BY	Hybertson, B.M. et al., "Deposition of Palladium Films by a Novel Supercritical Fluid Transport Chemical Deposition Process," Mat. Res. Bull., Vol. 26, pp. 1127-1133, 1991.
	BZ	Ziger, D. H. et al., "Compressed Fluid Technology: Application to RIE-Developed Resists," AiChE Jour., Vol. 33, No. 10, pp. 1585- 1591, October 1987.
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	CC	Joseph L. Foszcz, "Diaphragm Pumps Eliminate Seal Problems", Plant Engineering , pp. 1-5, February 1, 1996.
	CD	Bob Agnew, "WILDEN Air-Operated Diaphragm Pumps", Process & Industrial Training Technologies, Inc., 1996.
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Examiner:

Date Considered:

EXAMINER:

Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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ACKNOWLEDGEMENT RECEIPT

Electronic Version 1.1

Stylesheet Version v1.1.1

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER										
Submission Type:	Information Disclosure Statement										
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Page 2 of 2

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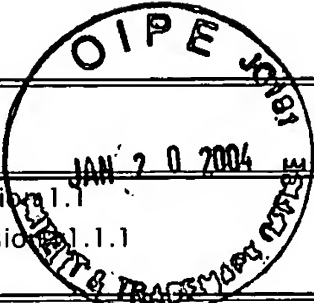
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Date:	2003-10-06						
First Named Applicant:	William Dale Jones						
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<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>							
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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<div>Application Number: 10/680783 *10/680783*</div> <div>Confirmation Number: 5859</div> <div>First Named Applicant: William Jones</div> <div>Attorney Docket Number:</div> <div>Search string: (6521466 or 6541278 or 6546946 or 6550484 or 6558475 or 6561213 or 6561220 or 6561481 or 6561767 or 6564826 or 5217043 or 20020001929).pn.</div>																																																																																																	
<div>US Patent Documents</div> <div>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</div> <table><thead><tr><th>Int</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>6521466</td><td>2002-02-18</td><td>Castrucci</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>2</td><td>6541278</td><td>2003-04-01</td><td>Morita et al.</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>3</td><td>6546946</td><td>2003-04-15</td><td>Dunmire</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>4</td><td>6550484</td><td>2003-04-22</td><td>Gopinath et al.</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>5</td><td>6558475</td><td>2003-05-06</td><td>Jur et al.</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>6</td><td>6561213</td><td>2003-05-13</td><td>Wang et al.</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>7</td><td>6561220</td><td>2003-05-13</td><td>McCullough et al.</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>8</td><td>6561481</td><td>2003-05-13</td><td>Filonczuk</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>9</td><td>6561767</td><td>2003-05-13</td><td>Biberger et al.</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>10</td><td>6564826</td><td>2003-05-20</td><td>Shen</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>11</td><td>5217043</td><td>1993-06-08</td><td>Novakovi</td><td></td><td></td><td></td></tr></tbody></table>		Int	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	6521466	2002-02-18	Castrucci	B1				2	6541278	2003-04-01	Morita et al.	B1				3	6546946	2003-04-15	Dunmire	B1				4	6550484	2003-04-22	Gopinath et al.	B1				5	6558475	2003-05-06	Jur et al.	B1				6	6561213	2003-05-13	Wang et al.	B1				7	6561220	2003-05-13	McCullough et al.	B1				8	6561481	2003-05-13	Filonczuk	B1				9	6561767	2003-05-13	Biberger et al.	B1				10	6564826	2003-05-20	Shen	B1				11	5217043	1993-06-08	Novakovi			
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Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER										
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Application Number:	10/680783 *10/680783*						
Date:	2003-10-06						
First Named Applicant:	William Dale Jones						
Confirmation Number:	5859						
Attorney Docket Number:							
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>							
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Submitted by:	Elec. Sign.	Sign. Capacity					
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Confirmation Number:	5859						
First Named Applicant:	William Jones						
Attorney Docket Number:							
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
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	3	3744660	1973-07-10	Gaines et al.			
	4	3968885	1976-07-13	Hassan et al.			
	5	4029517	1977-06-14	Rand			
	6	4091643	1978-05-30	Zucchini			
	7	4245154	1981-01-13	Uehara et al.			

8	4341592	1982-07-27	Shortes et al.
9	4355937	1982-10-26	Mack et al.
10	4367140	1983-01-04	Wilson
11	4406596	1983-09-27	Budde
12	4422651	1983-12-27	Platts
13	4474199	1984-10-02	Blaudszun
14	4522788	1995-06-11	Sitek et al.
15	4549467	1985-10-29	Wilden et al.
16	4592306	1986-06-03	Gallego
17	4601181	1986-07-22	Privat
18	4626509	1986-12-02	Lyman
19	4670126	1987-06-02	Messer et al.
20	4682937	1987-07-28	Credle, Jr.
21	4693777	1987-09-15	Hazano et al.
22	4749440	1988-06-07	Blackwood et al.
23	4778356	1988-10-18	Hicks
24	4788043	1988-11-29	Kagiyama et al.
25	4789077	1988-12-06	Noe
26	4823976	1989-04-25	White, III et al.
27	4825808	1989-05-02	Takahashi et al.
28	4827867	1989-05-09	Takei et al.
29	4838476	1989-06-13	Rahn
30	4865061	1989-09-12	Fowler et al.
31	4879431	1989-11-07	Bertoncini
32	4917556	1990-04-17	Stark et al
33	4924892	1990-05-15	Kiba et al.
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35	4960140	1990-10-02	Ishijima et al.
36	4983223	1991-01-08	Gessner
37	5011542	1991-04-30	Well
38	5044871	1991-09-03	Davis et al.
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46	5185296	1993-02-09	Morita et al.
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48	5188515	1993-02-23	Horn
49	5190373	1993-03-02	Dickson et al.
50	5191993	1993-03-09	Wanger et al.

Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal.
The current electronic filing contains part 1 out of a total of 4 electronic filings.

Signature

Examiner Name	Date

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1/12/2004

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ACKNOWLEDGEMENT RECEIPTElectronic Version 1.1
Stylesheet Version v1.1.1

Title of Invention

HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER

Submission Type: Information Disclosure Statement

Application Number: 10/680783

10/680783

EFS ID: 53497

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First Named Applicant: William Jones

Attorney Docket Number:

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1/12/2004

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Application Number:	10/680783 *10/680783*						
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First Named Applicant:	William Dale Jones						
Confirmation Number:	5859						
Attorney Docket Number:							
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Stylesheet Version v1.8.0

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	20	5337446	1994-08-16	Smith et al.
	21	5339844	1994-08-23	Stanford Jr. et al.
	22	5355901	1994-10-18	Mielnik et al.
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	25	5377705	1995-01-03	Smith, Jr. et al.
	26	5401322	1995-03-28	Marshall
	27	5404894	1995-04-11	Shirahwa
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	46	5706319	1998-01-06	Holtz
	47	5746008	1998-05-05	Yamashita et al.
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Remarks

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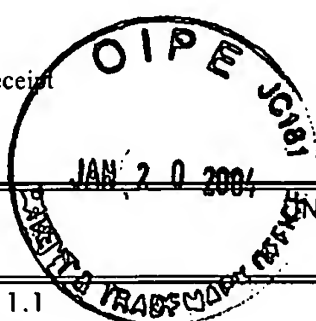
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Examiner Name	Date

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ACKNOWLEDGEMENT RECEIPT

Electronic Version 1.1

Stylesheet Version v1.1.1

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Application Number:	10/680783 *10/680783*						
Date:	2003-10-06						
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Confirmation Number:	5859						
Attorney Docket Number:							
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Attorney Docket Number:							
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	5	5904737	1999-05-18	Preston et al.			
	6	5928389	1999-07-27	Jevtic			
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	8	5934856	1999-08-10	Asakawa et al.	
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	47	6418956	2002-07-16	Bloom	B1
	48	6436824	2002-08-20	Chooi et al.	B1
	49	6454945	2002-09-24	Weigl et al.	B1
	50	6464790	2002-10-15	Shertinsky et al.	B1

Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal.
The current electronic filing contains part 3 out of a total of 4 electronic filings.

Signature

Examiner Name	Date